


# MATERIAL DECLARATION SHEET



Package Type	PTVS2-(066C-086C)-H			
Product Line	Semiconductor Products			
Compliance Date	21 <sup>th</sup> Jan 2022			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.1548	Amorphous Silica	60676-86-0	87.000	36.72645	38.06
				Solid Epoxy Resin 1	Proprietary	4.600	0.12380	
				Solid Epoxy Resin 2	Proprietary	4.490	0.10555	
				Phenol Resin	Proprietary	2.700	0.62283	
				Carbon Black	1333-86-4	0.700	0.22876	
				Crystalline Silica	14808-60-7	0.510	0.25490	
2	Leadframe	Copper Alloy	0.0618	Copper	7440-50-8	97.433	14.86141	15.19
				Iron	7439-89-6	2.350	0.31500	
				Phosphorus	7723-14-0	0.125	0.00498	
				Zinc	7440-66-6	0.083	0.01003	
				Lead	7439-92-1	0.010	0.00193	
3	Electrodes	Copper Alloy	0.0604	Copper	7440-50-8	95.485	14.04135	14.86
				Silver	7440-22-4	4.500	0.81240	
				Iron	7439-89-6	0.005	0.00065	
				Lead	7439-92-1	0.005	0.00093	
				Zinc	7440-66-6	0.003	0.00035	
				Phosphorous	7723-14-0	0.002	0.00008	
4	Chip	Silicon	0.0502	Silicon	7440-21-3	90.650	11.19008	12.34
				Nickel	7440-02-0	5.403	0.66698	
				Aluminum	7429-90-5	3.815	0.47092	
				Gold	7440-57-5	0.132	0.01626	
5	Solder Paste	Solder	0.0406	Lead*	7439-92-1	92.500	9.41725	9.99
				Tin	7440-31-5	5.000	0.32454	
				Silver	7440-22-4	2.500	0.24452	
6	Clip	Copper Alloy	0.0360	Copper	7440-50-8	95.485	8.37136	8.86
				Silver	7440-22-4	4.500	0.48435	
				Iron	7439-89-6	0.005	0.00038	
				Lead	7439-92-1	0.005	0.00055	
				Zinc	7440-66-6	0.003	0.00021	
				Phosphorous	7723-14-0	0.002	0.00005	
7	Terminal Finish	Tin	0.0029	Tin	7440-31-5	100.000	0.70115	0.70
		Total weight	0.4067					

\* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)